

Micropower 200 mA Low Dropout Tracking Regulator/Line Driver

The CS8182 is a monolithic integrated low dropout tracking regulator designed to provide an adjustable buffered output voltage that closely tracks (± 10 mV) the reference input. The output delivers up to 200 mA while being able to be configured higher, lower or equal to the reference voltages.

The device has been designed to operate over a wide range (2.8 V to 45 V) while still maintaining excellent DC characteristics. The CS8182 is protected from reverse battery, short circuit and thermal runaway conditions. The device also can withstand 45 V load dump transients and -50 V reverse polarity input voltage transients. This makes it suitable for use in automotive environments.

The V_{REF}/ENABLE lead serves two purposes. It is used to provide the input voltage as a reference for the output and it also can be pulled low to place the device in sleep mode where it nominally draws 30 μ A from the supply.

Features

- 200 mA Source Capability
- Output Tracks within ± 10 mV Worst Case
- Low Dropout (0.35 V Typ. @ 200 mA)
- Low Quiescent Current
- Thermal Shutdown
- Short Circuit Protection
- Wide Operating Range
- Internally Fused Leads in SO-8 Package
- For Automotive and Other Applications Requiring Site and Change Control
- These are Pb-Free Devices

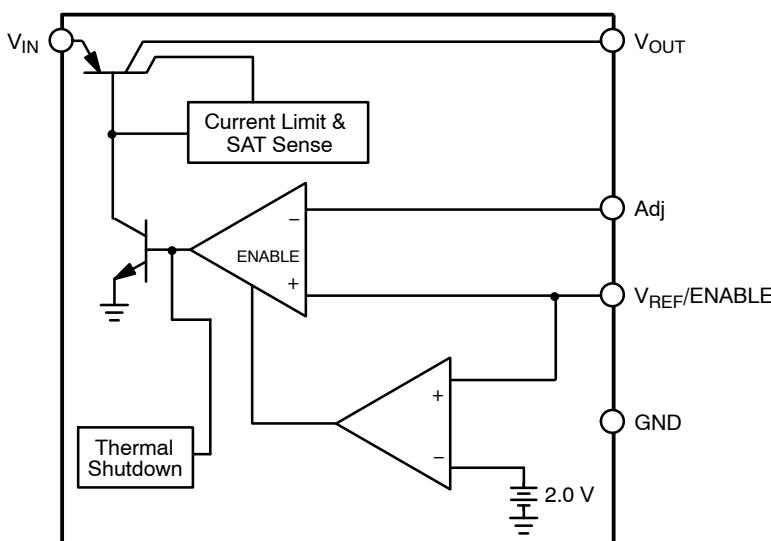
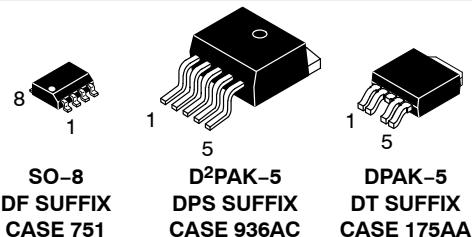


Figure 1. Block Diagram

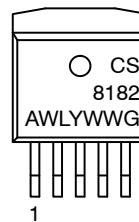


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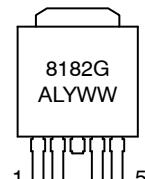
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PIN CONNECTIONS AND MARKING DIAGRAMS



Tab GND
Pin 1. V_{IN}
2. V_{OUT}
3. GND
4. Adj
5. V_{REF}



A = Assembly Location
WL, L = Wafer Lot
Y = Year
WW, W = Work Week
G or ■ = Pb-Free Device

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

PACKAGE PIN DESCRIPTION

Package Lead Number			Lead Symbol	Function
SO-8	D ² PAK 5-PIN	DPAK 5-PIN		
8	1	1	V _{IN}	Input Voltage
1	2	2	V _{OUT}	Regulated Output
2, 3, 6, 7	3	3	GND	Ground
4	4	4	Adj	Adjust Lead
5	5	5	V _{REF} /ENABLE	Reference Voltage and ENABLE Input

MAXIMUM RATINGS

Rating	Value	Unit
Storage Temperature Range	-65 to +150	°C
Junction Temperature	+150	°C
Supply Voltage Range (Continuous)	-16 to 45	V
Peak Transient Voltage (V _{IN} = 14 V, Load Dump Transient = 31 V)	45	V
Voltage Range (Adj, V _{OUT} , V _{REF} /ENABLE)	-10 to +V _{IN}	V
Package Thermal Resistance, SO-8: Junction-to-Case, R _{θJC} Junction-to-Air, R _{θJA}	25 80	°C/W °C/W
Package Thermal Resistance, D ² PAK Junction-to-Case, R _{θJC} Junction-to-Air, R _{θJA}	4.0 48	°C/W °C/W
Package Thermal Resistance, DPAK Junction-to-Case, R _{θJC} Junction-to-Air, R _{θJA}	8.0 64	°C/W °C/W
ESD Capability (Human Body Model) (Machine Model)	2.0 200	kV V
Lead Temperature Soldering: (Note 1)	(SO-8) (D ² PAK) (DPAK)	240 225 260
		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. 60 second maximum above 183°C.

RECOMMENDED OPERATING RANGES

Rating	Value	Unit
Junction Temperature, T _J	-40 to +125	°C
Input Voltage, Continuous V _{IN}	3.4 to 45	V

ELECTRICAL CHARACTERISTICS ($V_{IN} = 14$ V; $V_{REF}/ENABLE > 2.75$ V; $-40^\circ C < T_J < +125^\circ C$; $C_{OUT} \geq 10 \mu F$; $0.1 \Omega < C_{OUT-ESR} < 1.0 \Omega$ @ 10 kHz, unless otherwise specified.)

Parameter	Test Conditions	Min	Typ	Max	Unit
Regular Output					
$V_{REF} - V_{OUT}$ V_{OUT} Tracking Error	$4.5 V \leq V_{IN} \leq 26 V$, $100 \mu A \leq I_{OUT} \leq 200 mA$, Note 2 $V_{IN} = 12 V$, $I_{OUT} = 30 mA$, $V_{REF} = 5.0 V$, Note 2	-10 -5.0	-	10 5	mV mV
Dropout Voltage ($V_{IN} - V_{OUT}$)	$I_{OUT} = 100 \mu A$ $I_{OUT} = 30 mA$ $I_{OUT} = 200 mA$	- - -	100 - 350	150 500 600	mV mV mV
Line Regulation	$4.5 V \leq V_{IN} \leq 26 V$, Note 2	-	-	10	mV
Load Regulation	$100 \mu A \leq I_{OUT} \leq 200 mA$, Note 2	-	-	10	mV
Adj Lead Current	Loop in Regulation	-	0.2	1.0	μA
Current Limit	$V_{IN} = 14 V$, $V_{REF} = 5.0 V$, $V_{OUT} = 90\% \text{ of } V_{REF}$, Note 2	250	-	700	mA
Quiescent Current ($I_{IN} - I_{OUT}$)	$V_{IN} = 12 V$, $I_{OUT} = 200 mA$ $V_{IN} = 12 V$, $I_{OUT} = 100 \mu A$ $V_{IN} = 12 V$, $V_{REF}/ENABLE = 0 V$	- - -	15 75 30	25 150 55	mA μA μA
Reverse Current	$V_{OUT} = 5.0 V$, $V_{IN} = 0 V$	-	0.2	1.5	mA
Ripple Rejection	$f = 120$ Hz, $I_{OUT} = 200 mA$, $4.5 V \leq V_{IN} \leq 26 V$	60	-	-	dB
Thermal Shutdown	GBD	150	180	210	$^\circ C$

$V_{REF}/ENABLE$

Enable Voltage	-	0.80	2.00	2.75	V
Input Bias Current	$V_{REF}/ENABLE$	-	0.2	1.0	μA

2. V_{OUT} connected to Adj lead.

TYPICAL CHARACTERISTICS

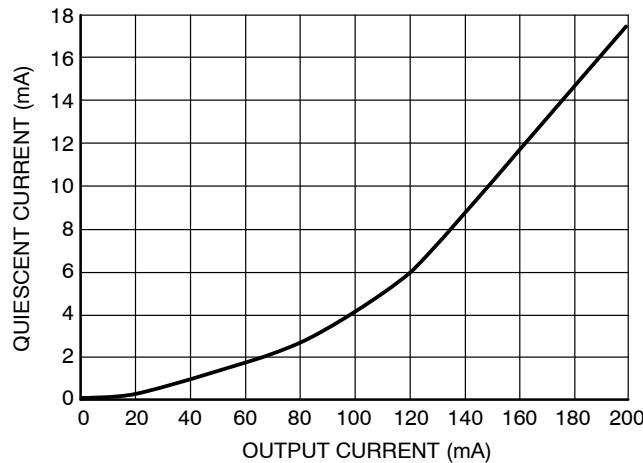


Figure 2. Quiescent Current vs. Output Current

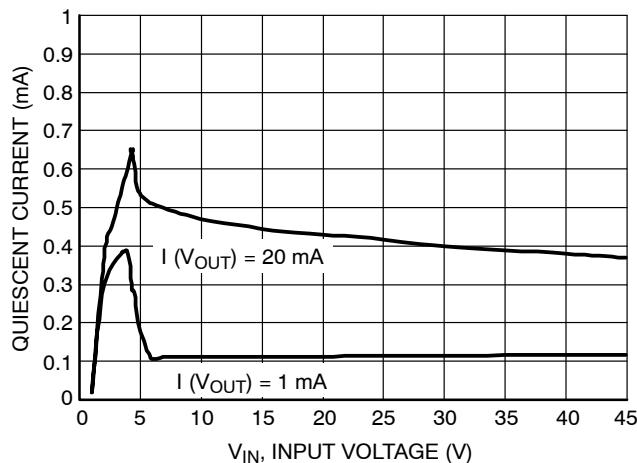


Figure 3. Quiescent Current vs. Input Voltage (Operating Mode)

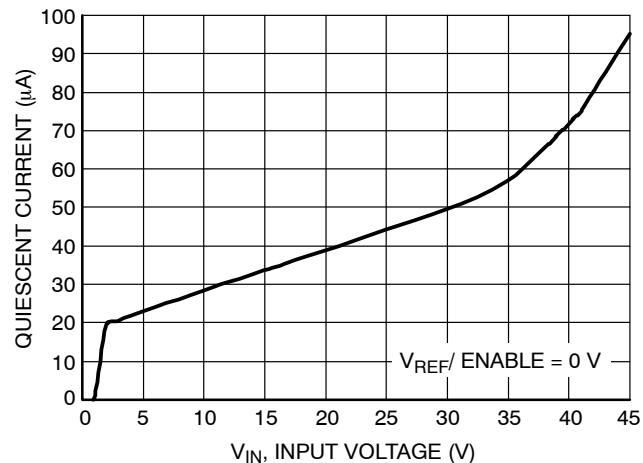
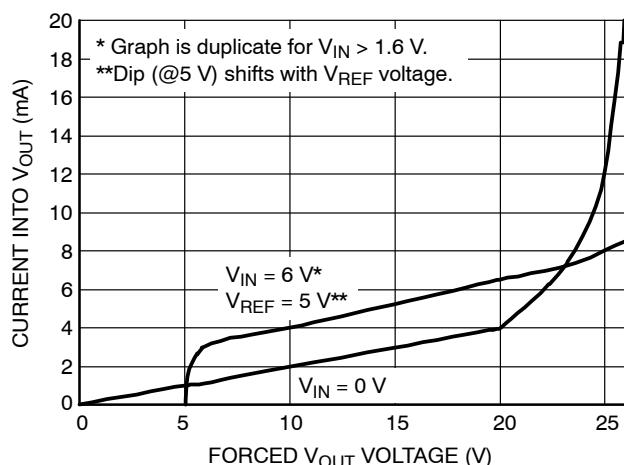
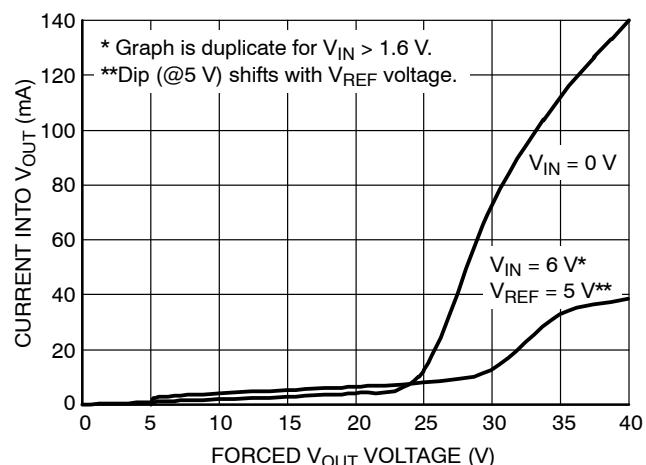


Figure 4. Quiescent Current vs. Input Voltage (Sleep Mode)

Figure 5. V_{OUT} Reverse CurrentFigure 6. V_{OUT} Reverse Current

CIRCUIT DESCRIPTION

ENABLE Function

By pulling the V_{REF}/ENABLE lead below 2.0 V typically, (see Figure 10 or Figure 11), the IC is disabled and enters a sleep state where the device draws less than 55 μ A from supply. When the V_{REF}/ENABLE lead is greater than 2.75 V, V_{OUT} tracks the V_{REF}/ENABLE lead normally.

Output Voltage

The output is capable of supplying 200 mA to the load while configured as a similar (Figure 7), lower (Figure 9), or higher (Figure 8) voltage as the reference lead. The Adj lead acts as the inverting terminal of the op amp and the V_{REF} lead as the non-inverting.

The device can also be configured as a high-side driver as displayed in Figure 12.

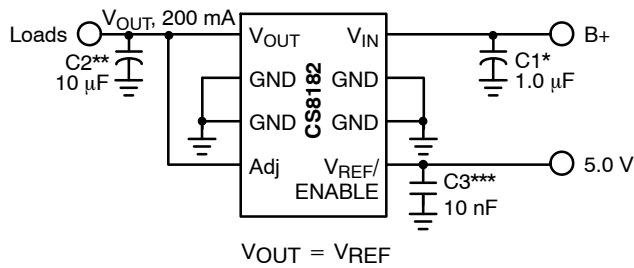


Figure 7. Tracking Regulator at the Same Voltage

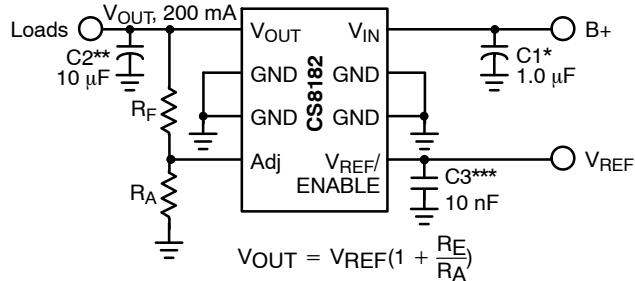


Figure 8. Tracking Regulator at Higher Voltages

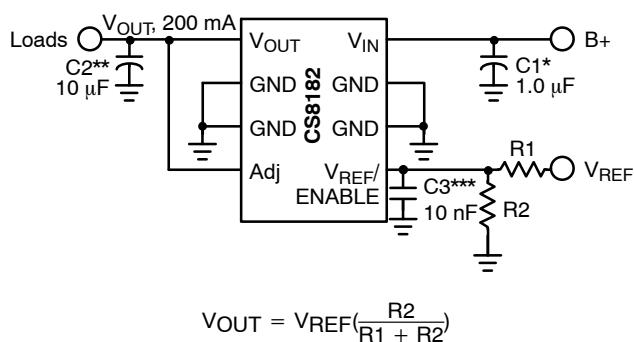


Figure 9. Tracking Regulator at Lower Voltages

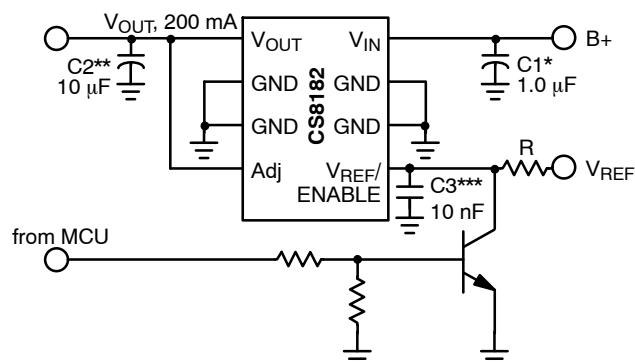


Figure 10. Tracking Regulator with ENABLE Circuit

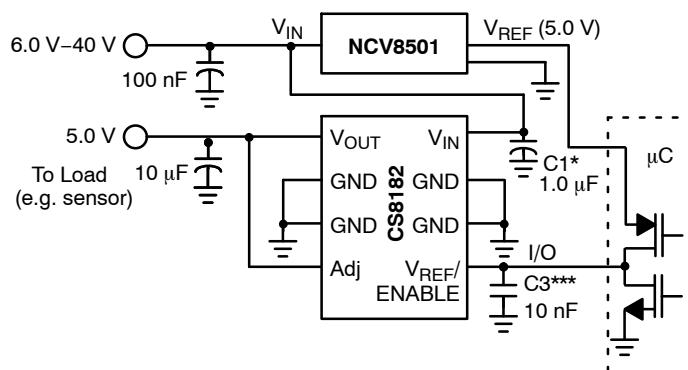


Figure 11. Alternative ENABLE Circuit

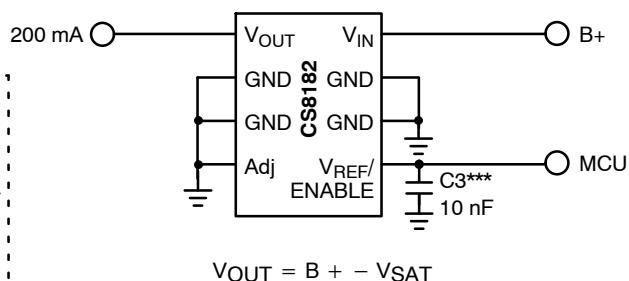


Figure 12. High-Side Driver

* C1 is required if the regulator is far from the power source filter.

** C2 is required for stability.

*** C3 is recommended for EMC susceptibility.

APPLICATION NOTES

V_{OUT} Short to Battery

The CS8182 will survive a short to battery when hooked up the conventional way as shown in Figure 13. No damage to the part will occur. The part also endures a short to battery when powered by an isolated supply at a lower voltage as in

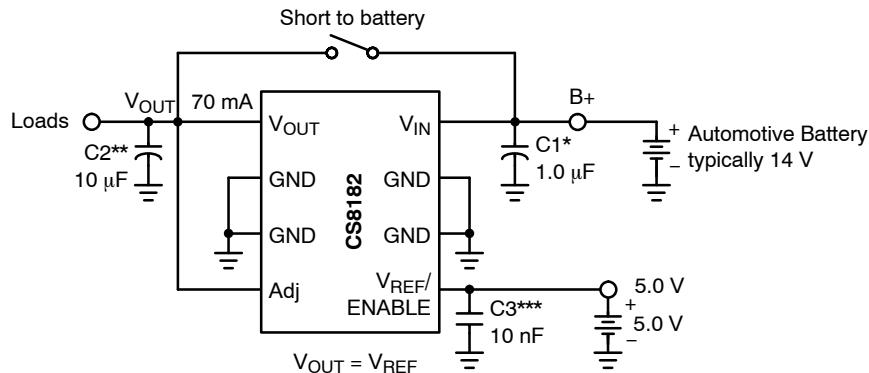
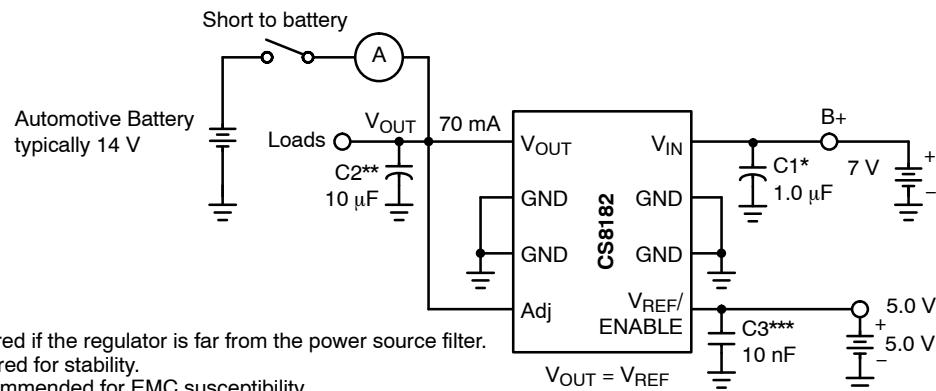


Figure 13.

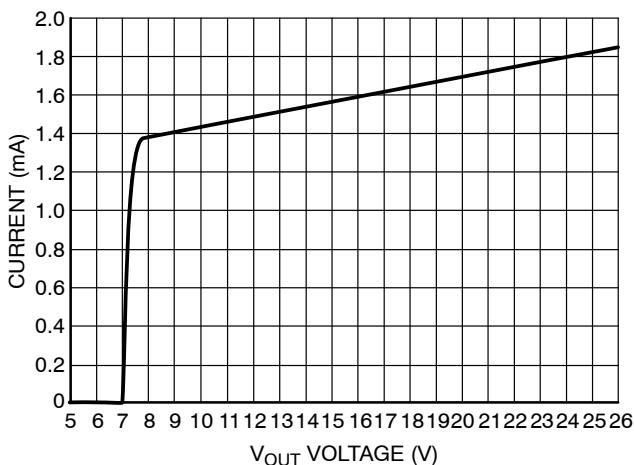


* C1 is required if the regulator is far from the power source filter.

** C2 is required for stability.

*** C3 is recommended for EMC susceptibility.

Figure 14.

Figure 15. V_{OUT} Short to Battery**Switched Application**

The CS8182 has been designed for use in systems where the reference voltage on the V_{REF/ENABLE} pin is continuously on. Typically, the current into the V_{REF/ENABLE} pin will be less than 1.0 μA when the voltage on the V_{IN} pin (usually the ignition line) has been switched out (V_{IN} can be at high impedance or at ground.) Reference Figure 16.

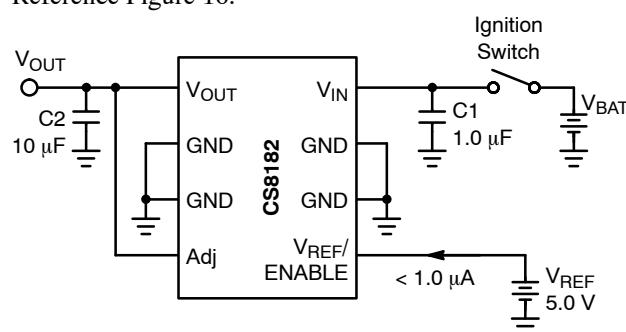


Figure 16.

External Capacitors

The output capacitor for the CS8182 is required for stability. Without it, the regulator output will oscillate. Actual size and type may vary depending upon the application load and temperature range. Capacitor effective series resistance (ESR) is also a factor in the IC stability. Worst-case is determined at the minimum ambient temperature and maximum load expected.

The output capacitor can be increased in size to any desired value above the minimum. One possible purpose of this would be to maintain the output voltage during brief conditions of negative input transients that might be characteristic of a particular system.

The capacitor must also be rated at all ambient temperatures expected in the system. To maintain regulator stability down to -40°C , a capacitor rated at that temperature must be used.

Calculating Power Dissipation in a Single Output Linear Regulator

The maximum power dissipation for a single output regulator (Figure 17) is:

$$\begin{aligned} \text{PD}(\text{max}) = & \{V_{\text{IN}}(\text{max}) - V_{\text{OUT}}(\text{min})\} I_{\text{OUT}}(\text{max}) \\ & + V_{\text{IN}}(\text{max}) I_{\text{Q}} \end{aligned} \quad (1)$$

where:

$V_{\text{IN}}(\text{max})$ is the maximum input voltage,

$V_{\text{OUT}}(\text{min})$ is the minimum output voltage,

$I_{\text{OUT}}(\text{max})$ is the maximum output current, for the application, and

I_{Q} is the quiescent current the regulator consumes at $I_{\text{OUT}}(\text{max})$.

Once the value of $\text{PD}(\text{max})$ is known, the maximum permissible value of R_{QJA} can be calculated:

$$R_{\text{QJA}} = \frac{150^{\circ}\text{C} - T_{\text{A}}}{\text{PD}} \quad (2)$$

The value of R_{QJA} can then be compared with those in the package section of the data sheet. Those packages with R_{QJA} 's less than the calculated value in equation 2 will keep the die temperature below 150°C .

In some cases, none of the packages will be sufficient to dissipate the heat generated by the IC, and an external heat sink will be required.

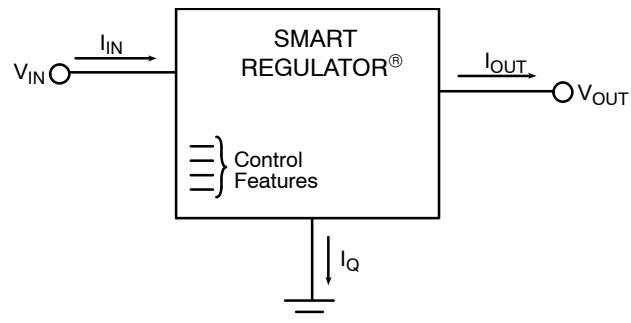


Figure 17. Single Output Regulator with Key Performance Parameters Labeled

Heatsinks

A heatsink effectively increases the surface area of the package to improve the flow of heat away from the IC and into the surrounding air.

Each material in the heat flow path between the IC and the outside environment will have a thermal resistance. Like series electrical resistances, these resistances are summed to determine the value of R_{QJA} :

$$R_{\text{QJA}} = R_{\text{QJC}} + R_{\text{QCS}} + R_{\text{QSA}} \quad (3)$$

where:

R_{QJC} = the junction-to-case thermal resistance,

R_{QCS} = the case-to-heatsink thermal resistance, and

R_{QSA} = the heatsink-to-ambient thermal resistance.

R_{QJC} appears in the package section of the data sheet. Like R_{QJA} , it is a function of package type. R_{QCS} and R_{QSA} are functions of the package type, heatsink and the interface between them. These values appear in heat sink data sheets of heatsink manufacturers.

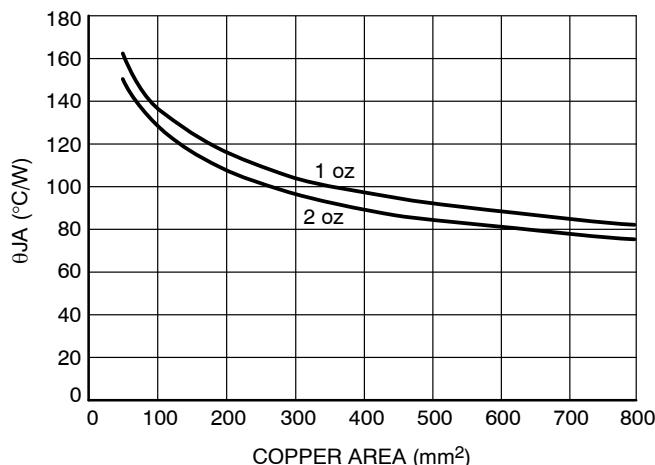


Figure 18. 8 Lead SOIC (Fused) Thermal Resistance

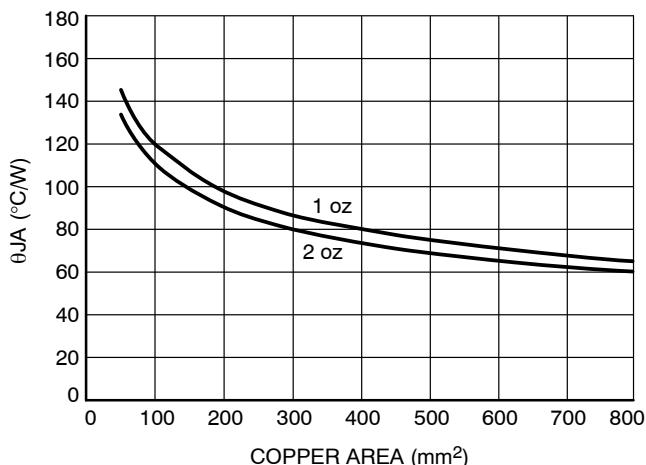


Figure 19. 5 Lead DPAK Thermal Resistance

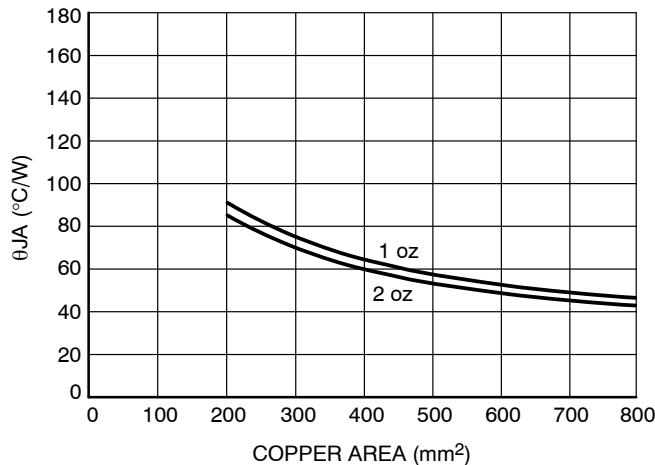


Figure 20. 5 Lead D²PAK Thermal Resistance

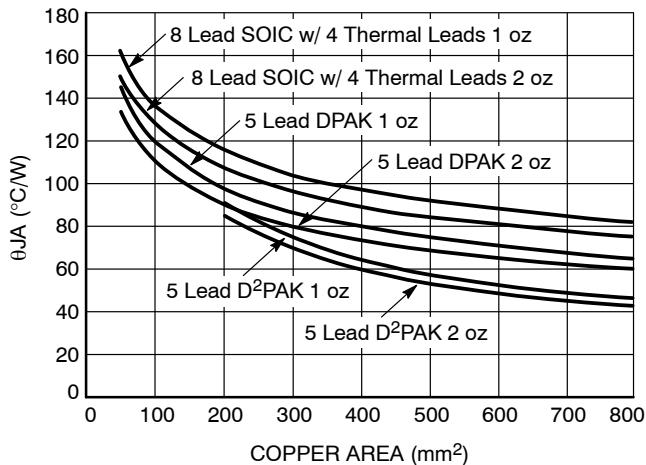


Figure 21. Thermal Resistance Summary

CS8182

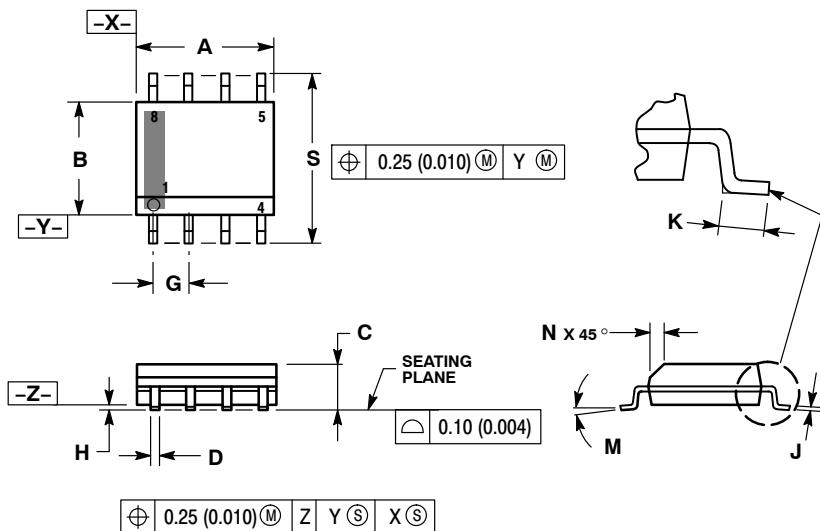
ORDERING INFORMATION

Device	Package	Shipping [†]
CS8182YDF8G	SO-8 (Pb-Free)	95 Units / Rail
CS8182YDFR8G	SO-8 (Pb-Free)	2500 / Tape & Reel
CS8182YDPS5G	D ² PAK 5-PIN (Pb-Free)	50 Units / Rail
CS8182YDPSR5G	D ² PAK 5-PIN (Pb-Free)	750 / Tape & Reel
CS8182DTG	DPAK 5L (Pb-Free)	50 Units / Rail
CS8182DTRKG	DPAK 5L (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SOIC-8
DF SUFFIX
CASE 751-07
ISSUE AK

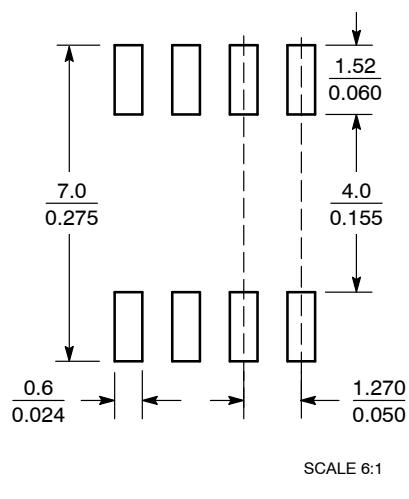


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0	8	0	8
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

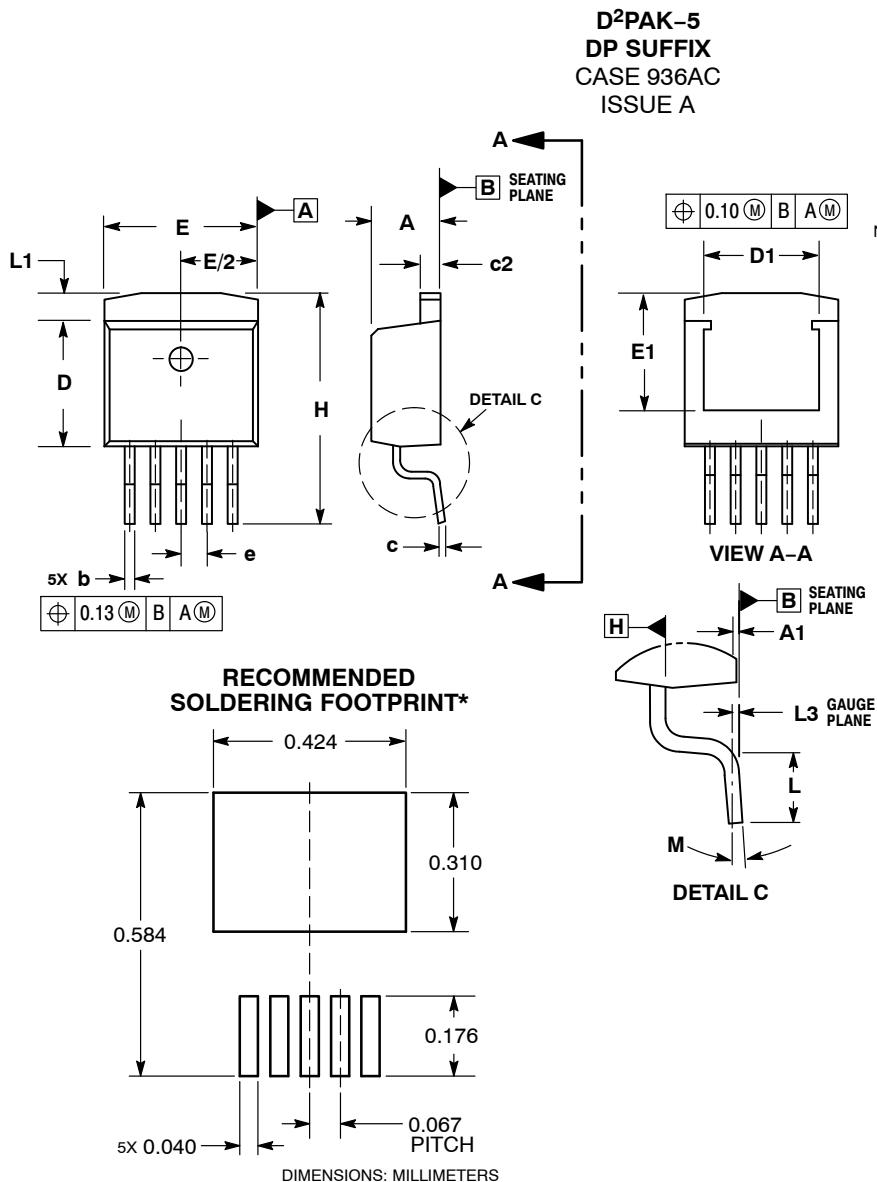
SOLDERING FOOTPRINT*



SCALE 6:1 $(\frac{\text{mm}}{\text{inches}})$

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS



NOTES:

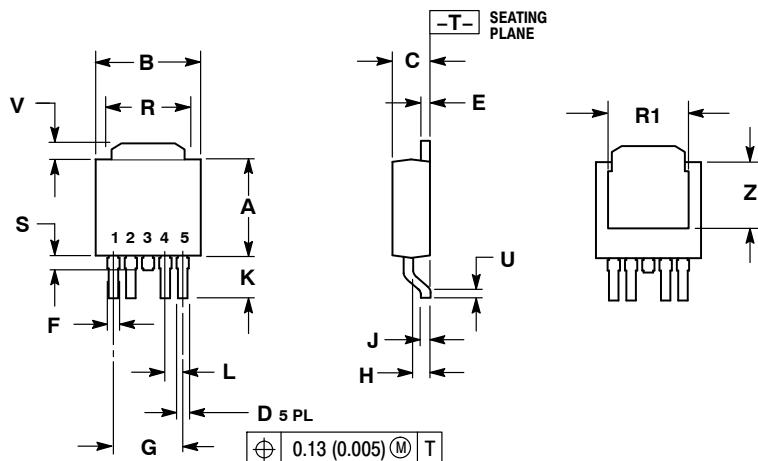
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH AND GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.005 MAXIMUM PER SIDE. THESE DIMENSIONS TO BE MEASURED AT DATUM H.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS E, L1, D1, AND E1. DIMENSIONS D1 AND E1 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THE THERMAL PAD.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.170	0.180	4.32	4.57
A1	0.000	0.010	0.00	0.25
b	0.026	0.036	0.66	0.91
c	0.017	0.026	0.43	0.66
c2	0.045	0.055	1.14	1.40
D	0.325	0.368	8.25	9.53
D1	0.250	---	6.35	---
E	0.380	0.420	9.65	10.67
E1	0.200	---	5.08	---
e	0.067 BSC	1.70 BSC		
H	0.580	0.620	14.73	15.75
L	0.090	0.110	2.29	2.79
L1	---	0.066	---	1.68
L3	0.010 BSC	0.25 BSC		
M	0 °	8 °	0 °	8 °

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

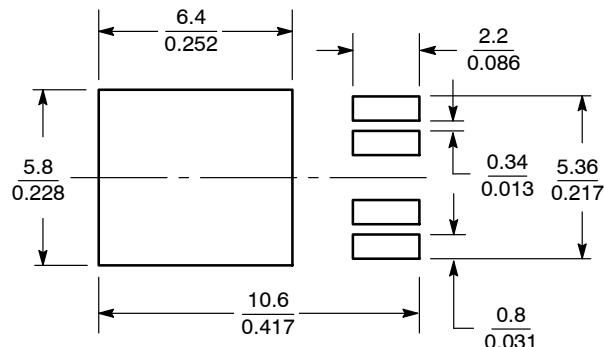
**DPAK-5
DT SUFFIX
CASE 175AA
ISSUE A**



NOTES:
 1. DIMENSIONING AND TOLERANCING
 PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.22
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.020	0.028	0.51	0.71
E	0.018	0.023	0.46	0.58
F	0.024	0.032	0.61	0.81
G	0.180	BSC	4.56	BSC
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.045	BSC	1.14	BSC
R	0.170	0.190	4.32	4.83
R1	0.185	0.210	4.70	5.33
S	0.025	0.040	0.63	1.01
U	0.020	---	0.51	---
V	0.035	0.050	0.89	1.27
Z	0.155	0.170	3.93	4.32

SOLDERING FOOTPRINT*



SCALE 4:1 $(\frac{\text{mm}}{\text{inches}})$

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Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помошь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помошь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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